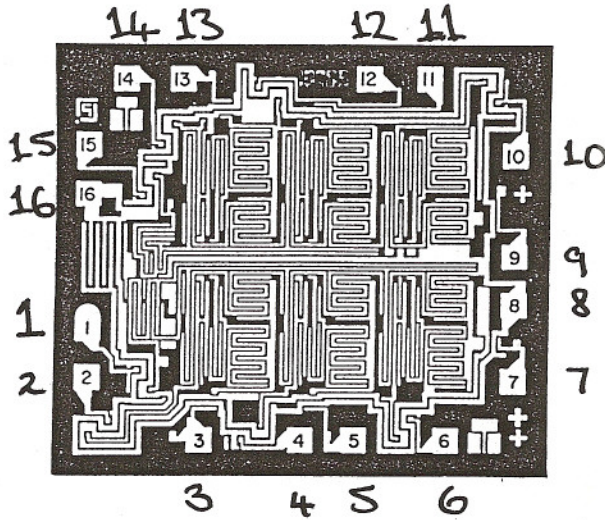




Sierra Components, Inc.

2222 Park Place • Suite 3E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>Pad</u>	<u>Function</u>	<u>Pad</u>	<u>Function</u>
1	DISABLE A	9	Q4
2	D1	10	D4
3	Q1	11	Q5
4	D2	12	D5
5	Q2	13	Q6
6	D3	14	D6
7	Q3	15	DISABLE B
8	V _{SS}	16	V _{DD}

Top Material: Al
Backside Material: Si
Bond Pad Size: 4 x 4
Backside Potential:
Mask Ref:

APPROVED BY: MG

DIE SIZE : 81 x 71

DATE: 10/27/08

MFG: HARRIS (RCA)

THICKNESS: 20

P/N: CD4503BH